Maximum Ratings (@T_A = +25°C, unless otherwise specified.)

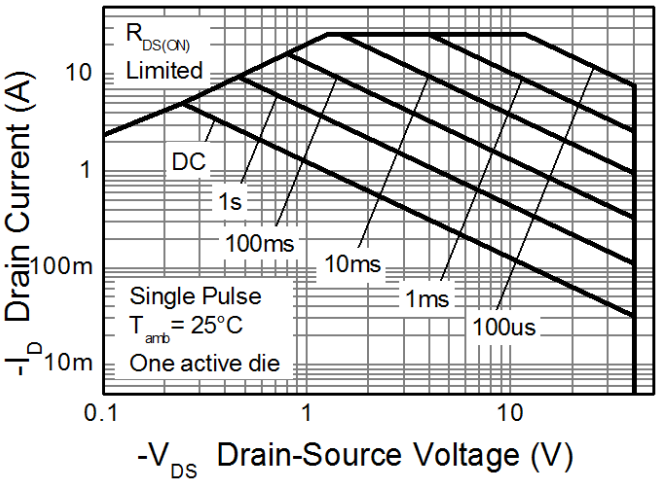
Characteristic			Symbol	Value	Units
Drain-Source Voltage			V_{DSS}	-40	V
Gate-Source Voltage			V_{GSS}	±20	
Continuous Drain Current	V_{GS} = -10V	(Notes 7 & 9)	I_D	-7.6	A
		T_A = +70°C (Notes 7 & 9)		-6.1	
		(Notes 6 & 9)		-5.8	
		(Notes 6 & 10)		-6.9	
Pulsed Drain Current	V_{GS} = -10V	(Notes 8 & 9)	I_{DM}	-28.0	
Continuous Source Current (Body diode)		(Notes 7 & 9)	I_S	-3.0	
Pulsed Source Current (Body diode)		(Notes 8 & 9)	I_{SM}	-28.0	

Thermal Characteristics (@T_A = +25°C, unless otherwise specified.)

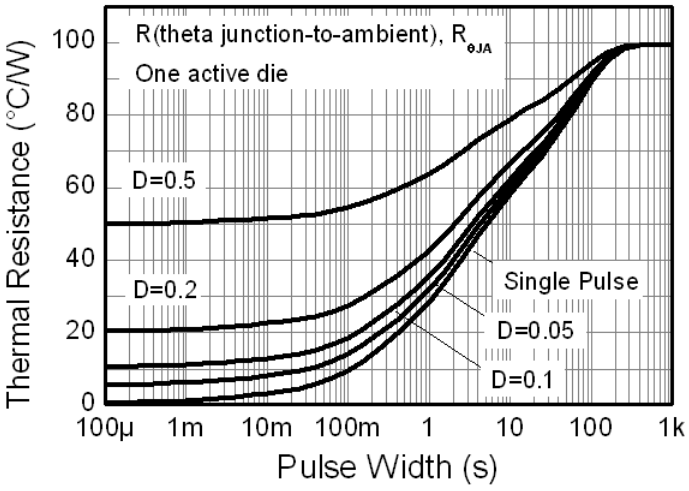
Characteristic		Symbol	Value	Unit
Power Dissipation Linear Derating Factor	(Notes 6 & 9)	P_D	1.25 10	W mW/°C
	(Notes 6 & 10)		1.8 14.3	
	(Notes 7 & 9)		2.14 17.2	
Thermal Resistance, Junction to Ambient	(Notes 6 & 9)	$R_{\theta JA}$	100	°C/W
	(Notes 6 & 10)		70	
	(Notes 7 & 9)		58	
Thermal Resistance, Junction to Lead	(Notes 9 & 11)	$R_{\theta JL}$	51	
Operating and Storage Temperature Range		T_J, T_{STG}	-55 to +150	°C

Notes:
6. For a device surface mounted on 25mm x 25mm x 1.6mm FR4 PCB with high coverage of single sided 1oz copper, in still air conditions; the device is measured when operating in a steady-state condition.
7. Same as note (2), except the device is measured at t ≤ 10 sec.
8. Same as note (2), except the device is pulsed with D = 0.02 and pulse width 300µs.
9. For a dual device with one active die.
10. For a device with two active die running at equal power.
11. Thermal resistance from junction to solder-point (at the end of the drain lead).

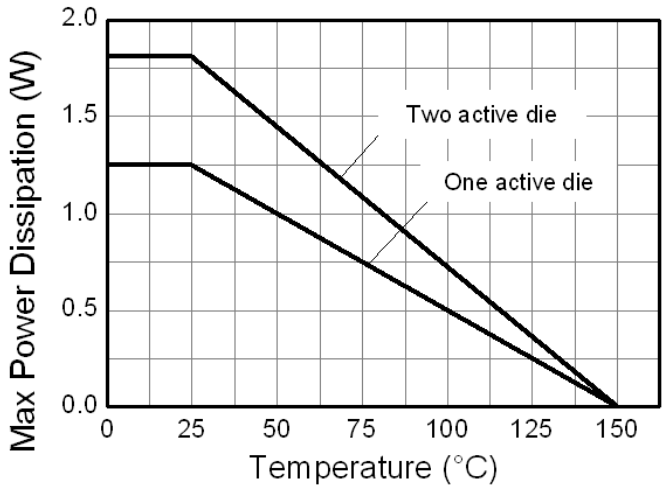
Thermal Characteristics



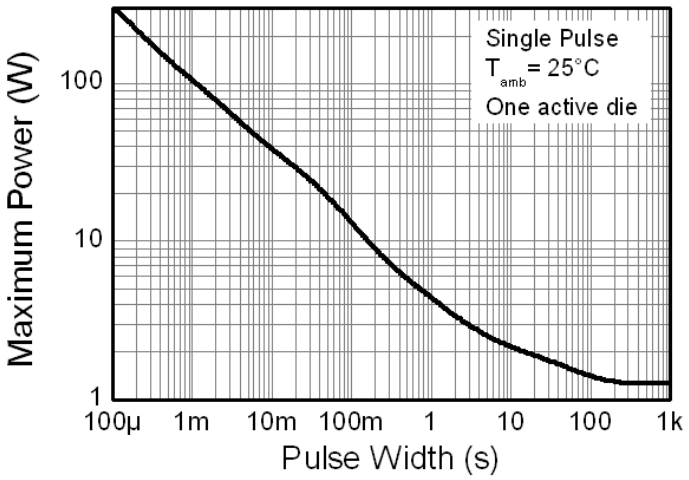
P-channel Safe Operating Area



Transient Thermal Impedance



Derating Curve



Pulse Power Dissipation

Electrical Characteristics (@T_A = +25°C, unless otherwise specified.)

Characteristic	Symbol	Min	Typ	Max	Unit	Test Condition
OFF CHARACTERISTICS						
Drain-Source Breakdown Voltage	BV_{DSS}	-40	—	—	V	I_D = -250μA, V_{GS} = 0V
Zero Gate Voltage Drain Current	I_{DSS}	—	—	-1.0	μA	V_{DS} = -40V, V_{GS} = 0V
Gate-Source Leakage	I_{GSS}	—	—	±100	nA	V_{GS} = ±20V, V_{DS} = 0V
ON CHARACTERISTICS						
Gate Threshold Voltage	$V_{GS(th)}$	-0.8	-1.3	-1.8	V	I_D = -250 μA, V_{DS} = V_{GS}
Static Drain-Source On-Resistance (Note 12)	$R_{DS\ (ON)}$	—	18	25	mΩ	V_{GS} = -10V, I_D = -3A
			30	45		V_{GS} = -4.5V, I_D = -3A
Forward Transconductance (Notes 12 & 13)	g_{fs}	—	16.6	—	S	V_{DS} = -5V, I_D = -3A
Diode Forward Voltage (Note 12)	V_{SD}	—	-0.7	-1.0	V	I_S = -1A, V_{GS} = 0V
DYNAMIC CHARACTERISTICS (Note 13)						
Input Capacitance	C_{iss}	—	1640	—	pF	V_{DS} = -20V, V_{GS} = 0V f = 1MHz
Output Capacitance	C_{oss}	—	179	—		
Reverse Transfer Capacitance	C_{rss}	—	128	—		
Gate Resistance	R_g	—	6.43	—	Ω	V_{DS} = 0V, V_{GS} = 0V, f = 1MHz
Total Gate Charge (Note 14)	Q_g	—	14.0	—	nC	V_{GS} = -4.5V; V_{DS} = -20V, I_D = -3A
Total Gate Charge (Note 14)	Q_g	—	33.7	—		V_{GS} = -10V; V_{DS} = -20V, I_D = -3A
Gate-Source Charge (Note 14)	Q_{gs}	—	5.5	—		
Gate-Drain Charge (Note 14)	Q_{gd}	—	7.3	—		
Turn-On Delay Time (Note 14)	$t_{D(on)}$	—	6.9	—	ns	V_{DD} = -20V, V_{GS} = -10V I_D = -3A
Turn-On Rise Time (Note 14)	t_r	—	14.7	—		
Turn-Off Delay Time (Note 14)	$t_{D(off)}$	—	53.7	—		
Turn-Off Fall Time (Note 14)	t_f	—	30.9	—		

Notes: 12. Measured under pulsed conditions. Pulse width ≤ 300μs; duty cycle ≤ 2%
13. For design aid only, not subject to production testing.
14. Switching characteristics are independent of operating junction temperatures.

Typical Characteristics

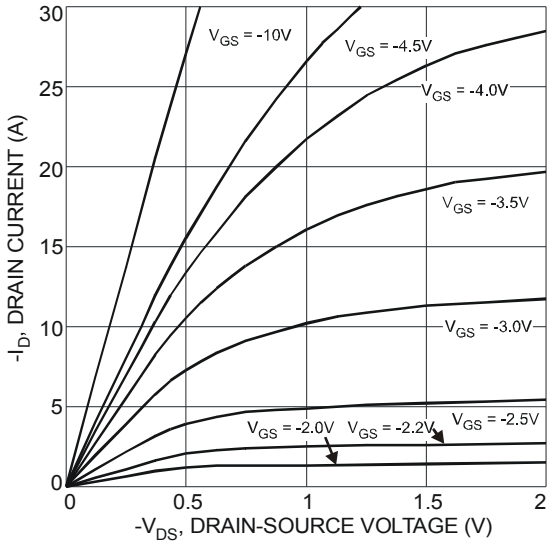


Fig. 1 Typical Output Characteristic

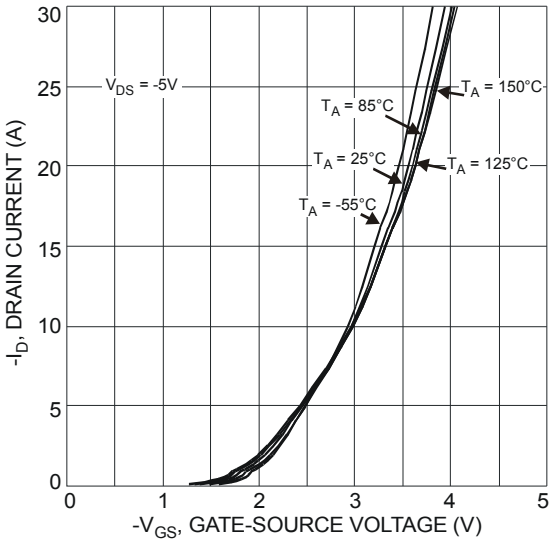


Fig. 2 Typical Transfer Characteristic

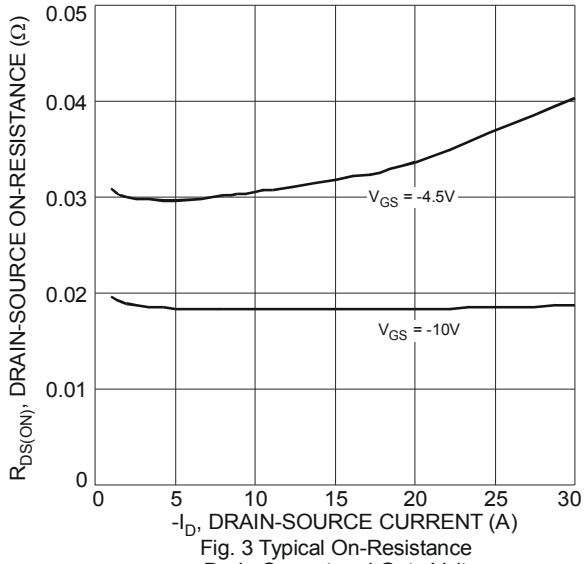


Fig. 3 Typical On-Resistance
vs. Drain Current and Gate Voltage

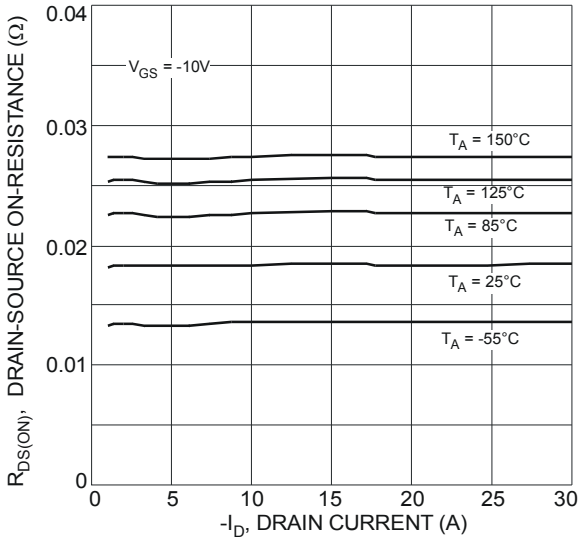


Fig. 4 Typical On-Resistance
vs. Drain Current and Temperature

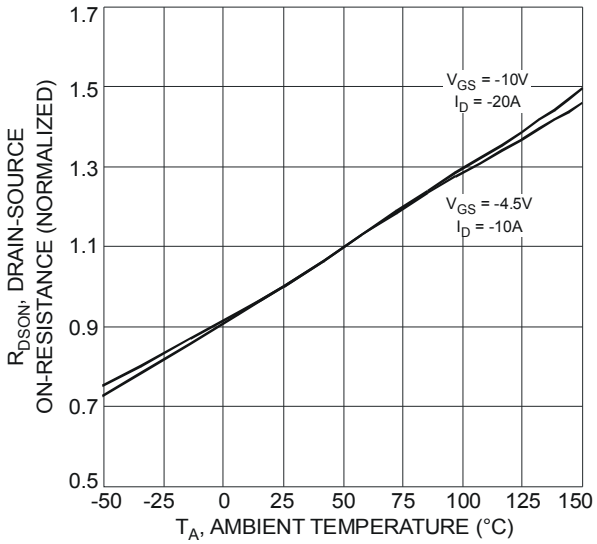


Fig. 5 On-Resistance Variation with Temperature

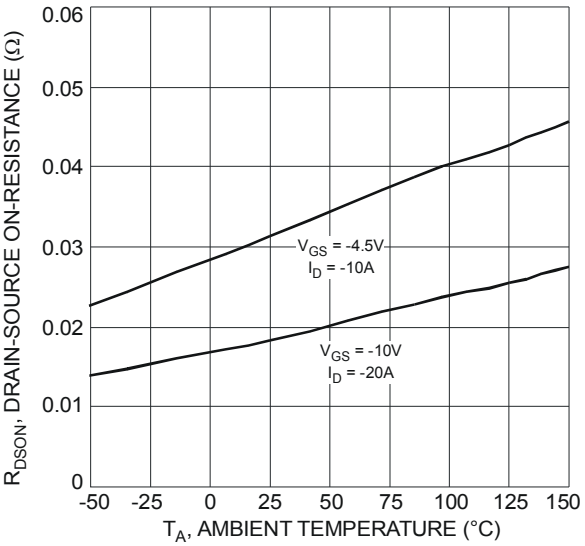


Fig. 6 On-Resistance Variation with Temperature

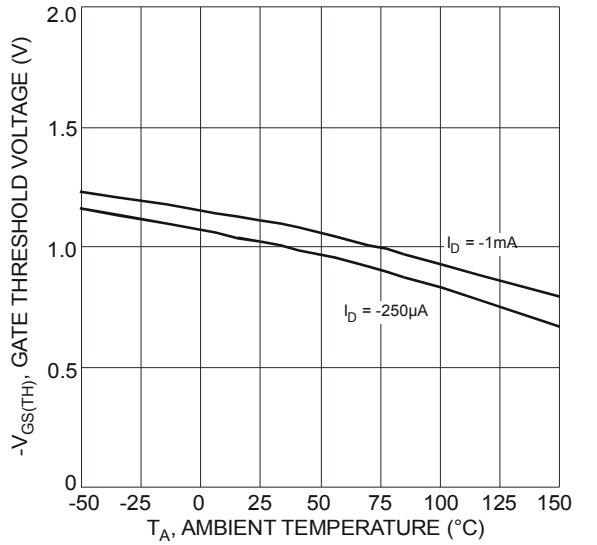


Fig. 7 Gate Threshold Variation vs. Ambient Temperature

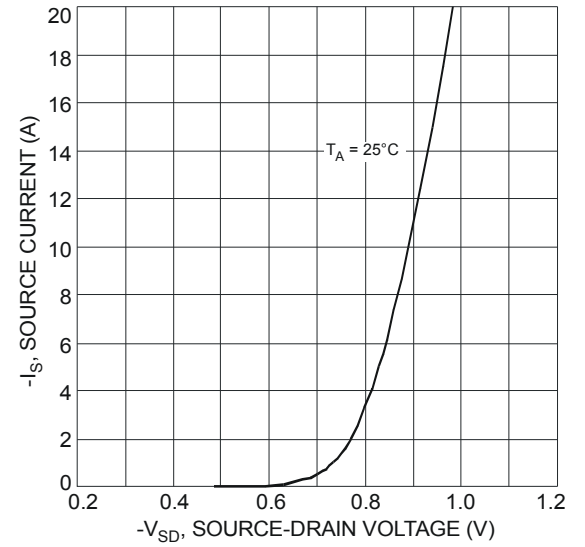


Fig. 8 Diode Forward Voltage vs. Current

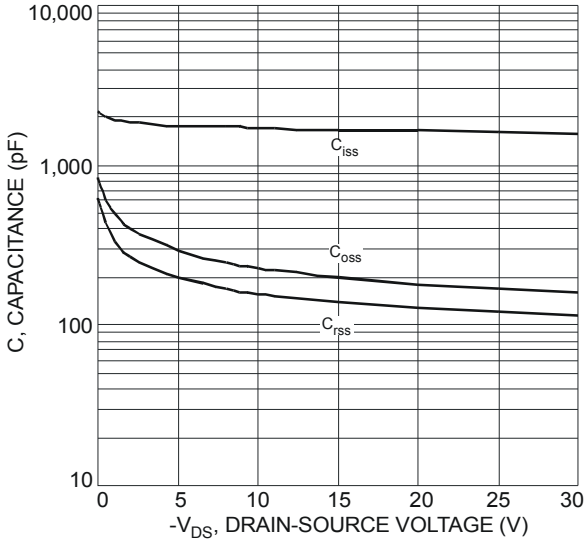


Fig. 9 Typical Total Capacitance

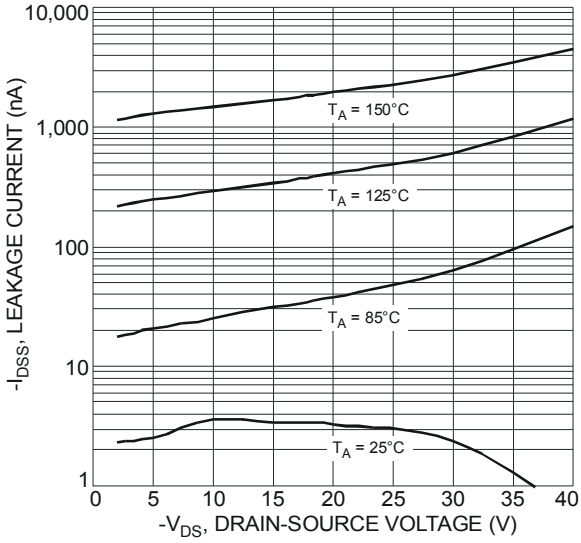


Fig. 10 Typical Leakage Current
vs. Drain-Source Voltage

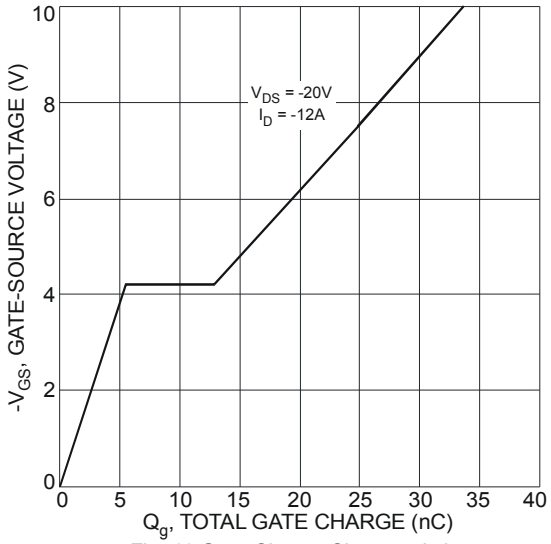
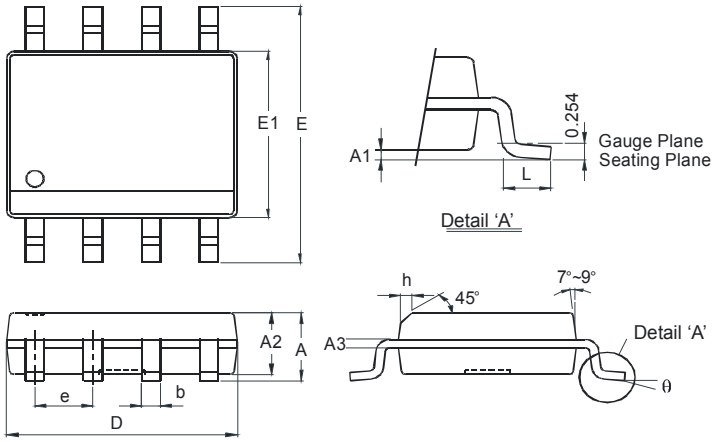


Fig. 11 Gate-Charge Characteristics

Package Outline Dimensions

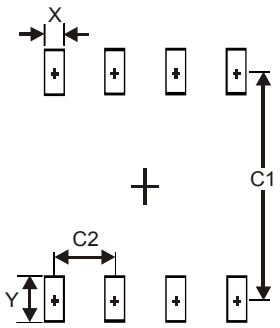
Please see AP02002 at http://www.diodes.com/datasheets/ap02002.pdf for latest version.



SO-8		
Dim	**Min**	**Max**
A	-	1.75
A1	0.10	0.20
A2	1.30	1.50
A3	0.15	0.25
b	0.3	0.5
D	4.85	4.95
E	5.90	6.10
E1	3.85	3.95
e	1.27 Typ	
h	-	0.35
L	0.62	0.82
θ	0°	8°
All Dimensions in mm		

Suggested Pad Layout

Please see AP02001 at http://www.diodes.com/datasheets/ap02001.pdf for the latest version.



Dimensions	Value (in mm)
X	0.60
Y	1.55
C1	5.4
C2	1.27

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